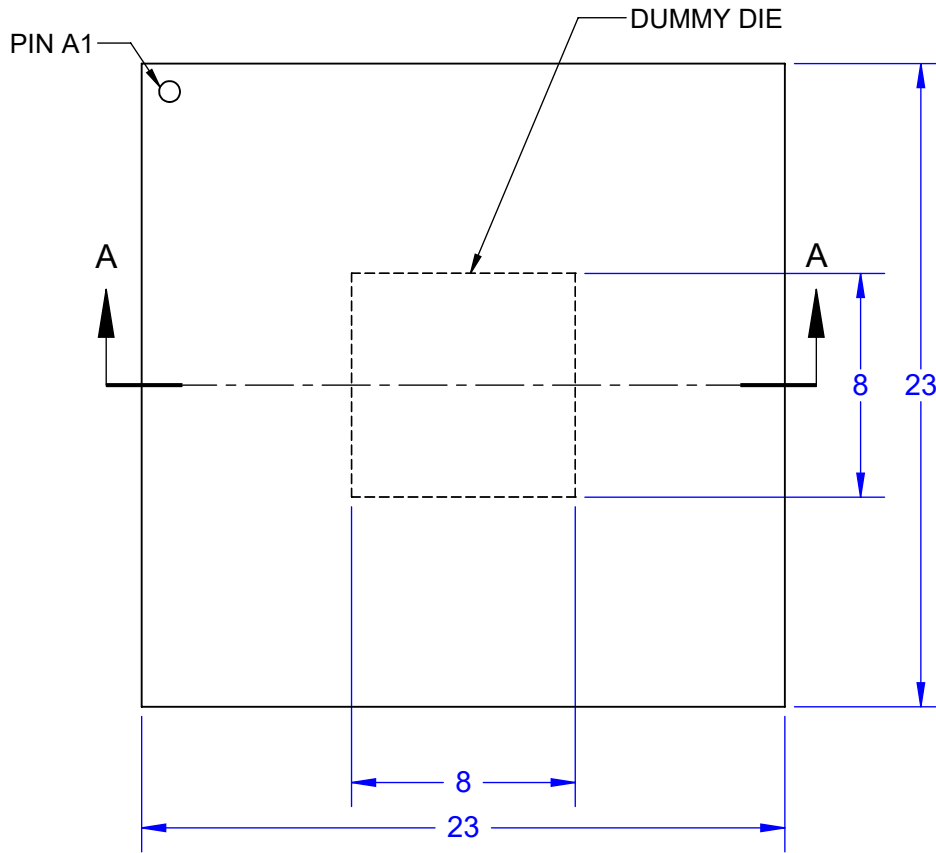
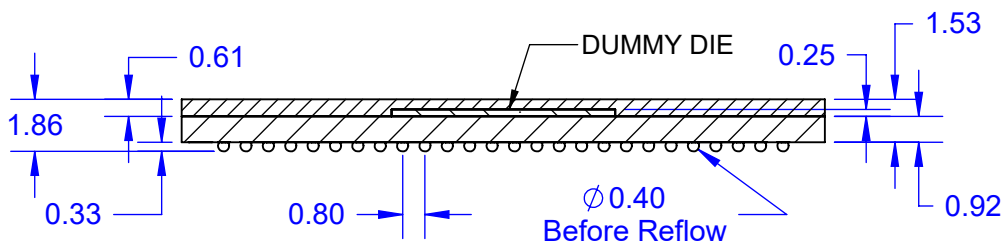
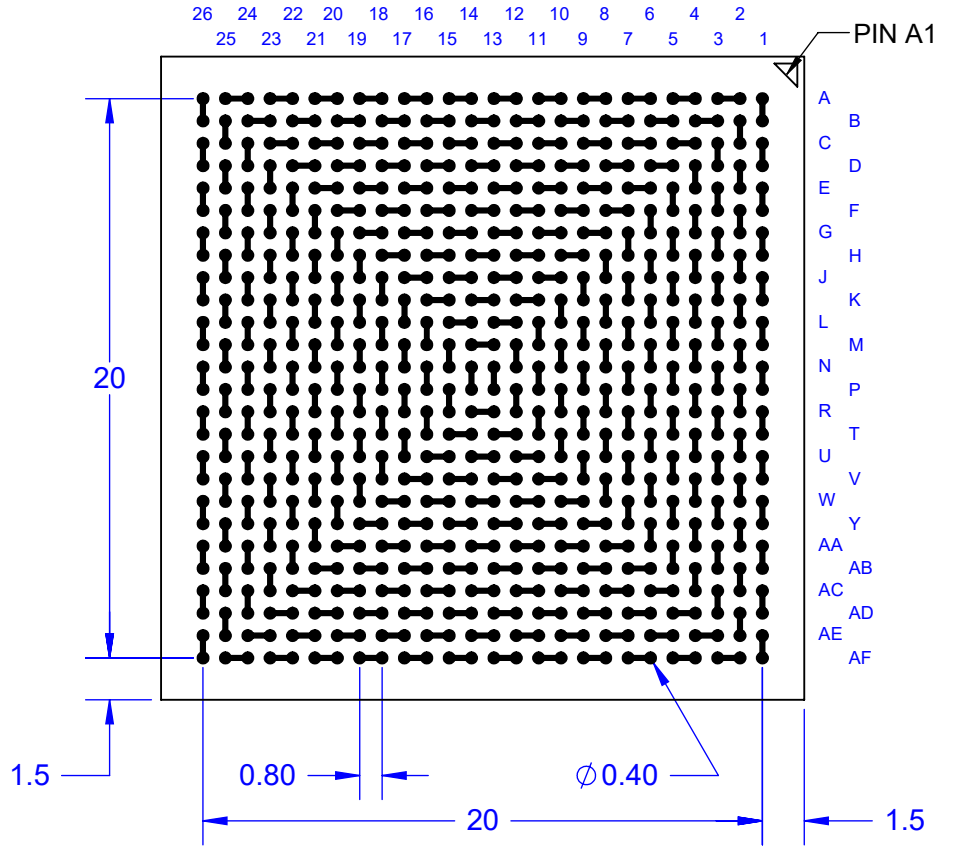


TOP VIEW



BALL VIEW



SECTION A-A

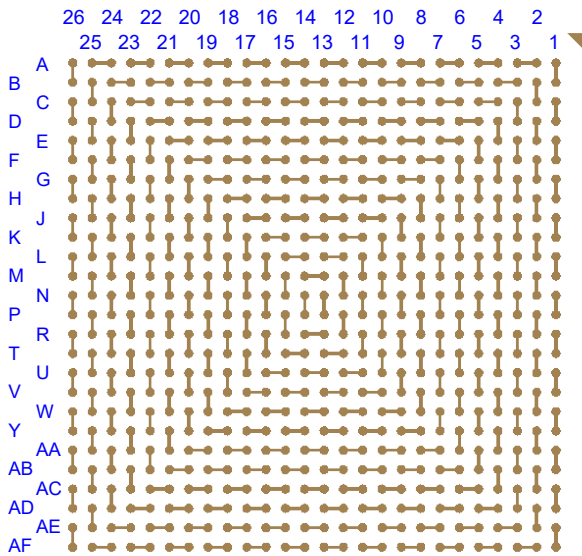
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm (13 MIL).
- 5) PAD Cu DIAMETER: 0.40mm (16 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

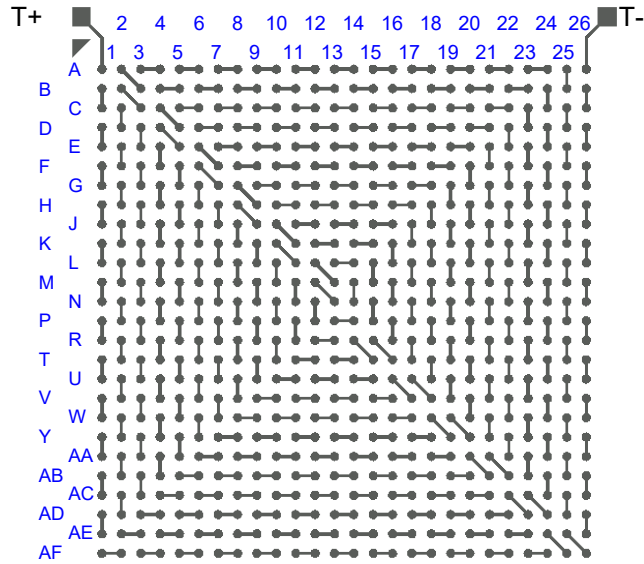
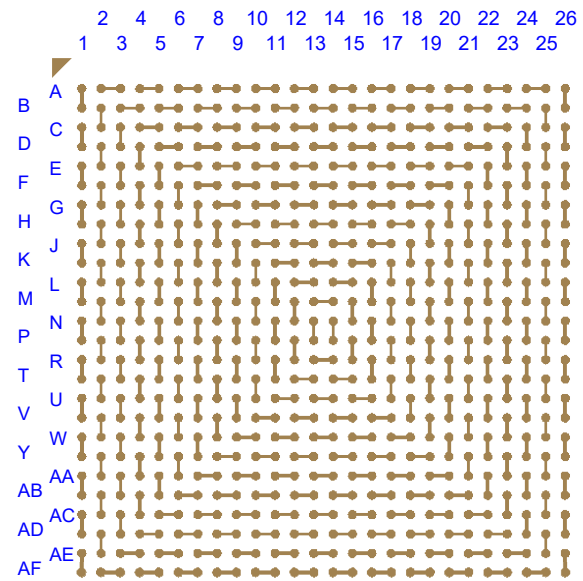
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA676T.8C-DC269D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA676T.8-DC269D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE	TopLine®			
DRAWN T.Au	6/08/2025				
ENG M. Hart	6/08/2025	TITLE BGA676T.8-DC269 DAISY CHAIN DUMMY			
MFG		SCALE 3.7:1	SIZE A	DRAWING NO. 582690	REV B
QA		DO NOT SCALE DRAWING			SHEET 1 OF 4
CUST					
REVISED					

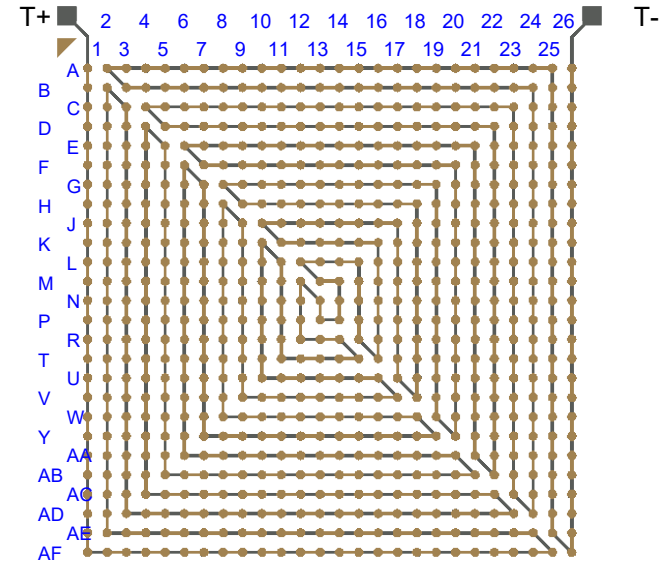
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



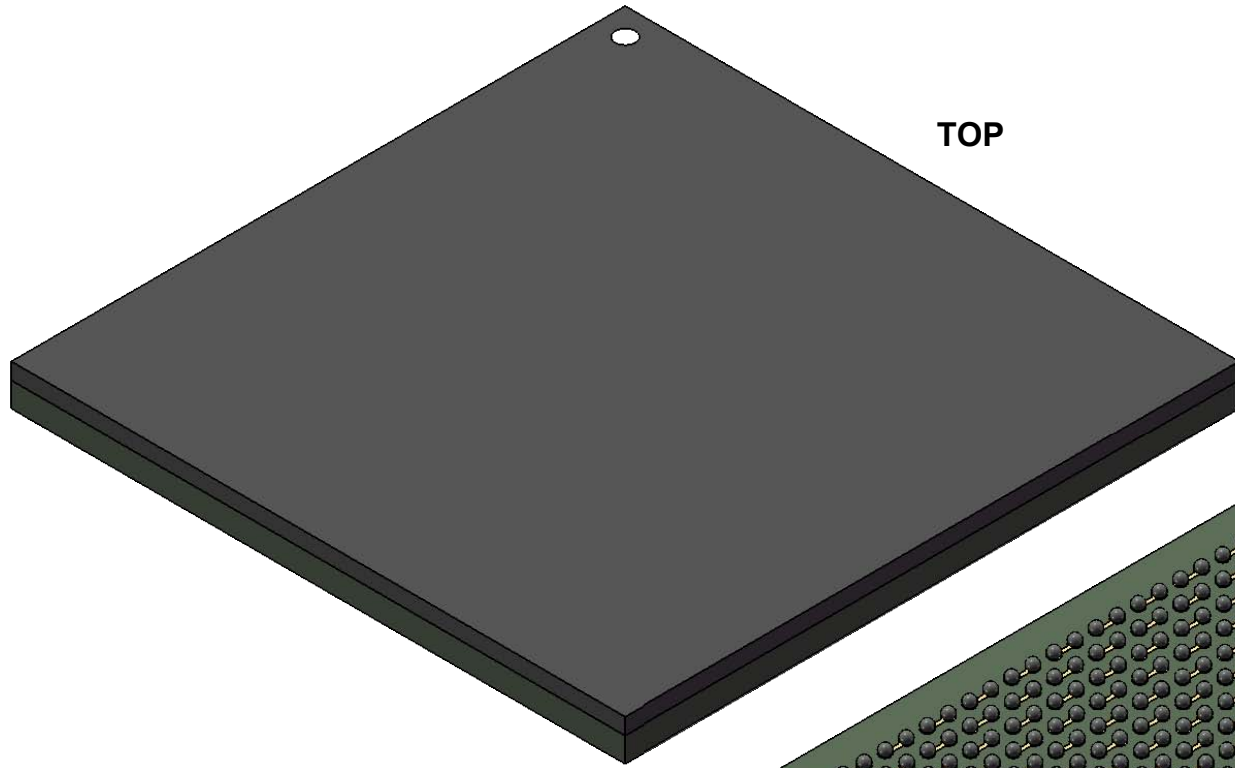
AFTER MOUNTING

Notes:

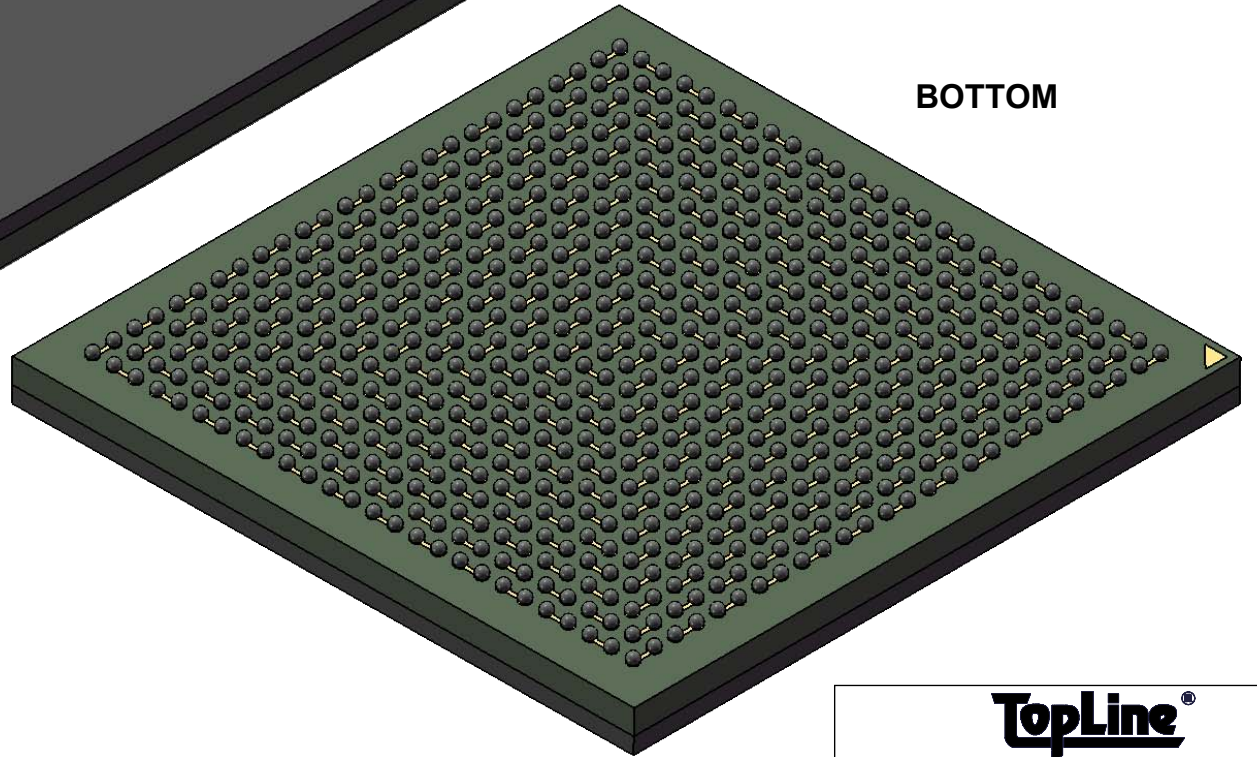
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.40mm (16 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.33mm (13 MIL).

TopLine®			
TITLE		BGA676T.8-DC269 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	582690	B
DO NOT SCALE DRAWING			SHEET 2 OF 4

MODEL



TOP



BOTTOM

TopLine[®]

TITLE BGA676T.8-DC269D
DAISY CHAIN DUMMY

SCALE	SIZE	DRAWING NO.	REV
3:1	A	582690	B

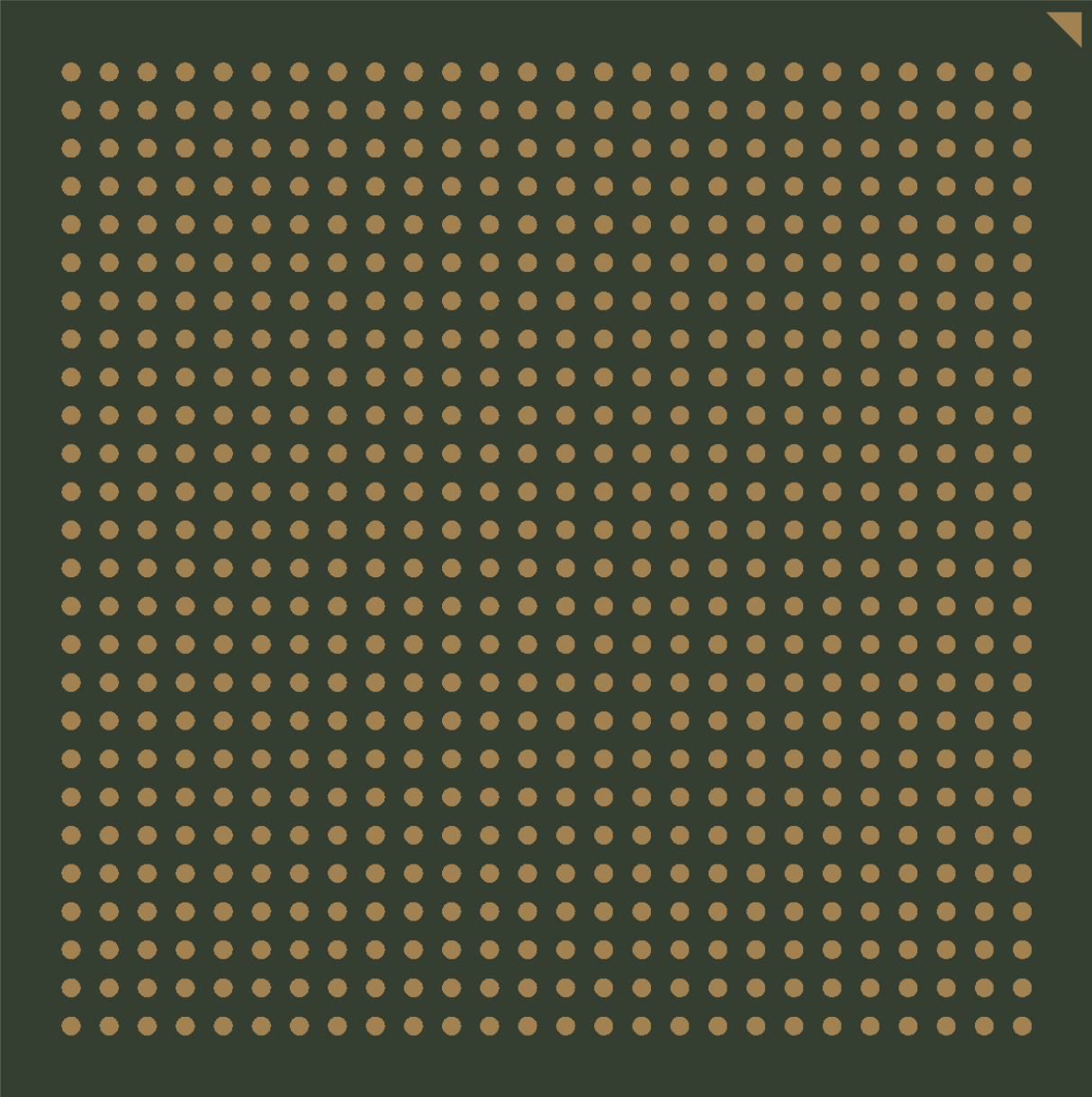
DO NOT SCALE DRAWING

SHEET 3 OF 4

**BOTTOM SOLDER MASK
(RIGHT READING)**

26 24 22 20 18 16 14 12 10 8 6 4 2
25 23 21 19 17 15 13 11 9 7 5 3 1

A
B
C
D
E
F
G
H
J
K
L
M
N
P
R
T
U
V
W
Y
AA
AB
AC
AD
AE
AF



TopLine®			
TITLE		BGA676T.8-DC269D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	582690	B
DO NOT SCALE DRAWING			SHEET 4 OF 4